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Applicant Shigeru Okamoto

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## U.S. PATENT DOCUMENTS

Examiner initial*	Document No.	Date	Name	Class	Subclass	Filing Date
KB	4,990,997	Feb. 5, 1991	Nishida	357	71	Apr. 14, 1989
KB	5,070,036	Dec. 3, 1991	Stevens	437	180	May 18, 1990
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KB	5,464,666	Nov. 7, 1995	Fine et al.	427	576	Feb. 6, 1995
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KB	John A.T. Norman, David A. Roberts et al., ENHANCED DEPOSITION OF COPPER FILMS BY CVD - Advanced Metalization for ULSI Application pp. 57-62
KB	Susan L. Cohen, Michael Liehr and Srinandan Kasi, Mechanisms of copper chemical vapor depositions, Appl. Phys. Lett. 60 (1), January 6, 1992, pp. 50-52

Examiner

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Date Considered

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\*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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